

**LEADFRAME HAVING FINE PITCH BOND FINGERS
FORMED USING LASER CUTTING METHOD**

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ABSTRACT OF THE DISCLOSURE

Methods of making a leadframe and a semiconductor package made using the leadframe are disclosed. One embodiment of such a method includes providing a metal sheet and patterning the metal sheet to form a plurality of leads. An inner end portion of each lead is joined into a block with the inner end portion of one or more adjacent leads. Subsequently, the end block is cut with a laser to singulate the inner end portion of each of the leads from the end block. This method can further comprise reducing a thickness of the end block relative to an initial thickness of the metal sheet, prior to the laser cutting step, to make the laser cutting easier.